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HZT33

Monolithic IC Zener Diode for Temperature Compensation



ADE-208-135D (Z)

Rev.4 Apr. 2002

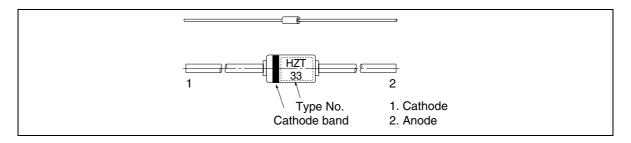
Features

- Lower temperature coefficient of the reference voltage.
- Lower dynamic resistance.
- High reliability with glass seal.

Ordering Information

Type No.	Mark	Package Code	
HZT33	Type No.	DO-35	

Pin Arrangement



HZT33

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Operation temperature	Topr	−20 to +75	°C
Storage temperature	Tstg	-40 to +175	°C

Note: Value at Ta = 75°C.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener Voltage	V _z	31.0	_	35.0	V	$I_z = 5 \text{ mA}$
Dynamic resistance	r _d	_	_	25.0	Ω	$I_z = 5 \text{ mA}, f = 1 \text{ KHz}$
Temperature coefficient	γ_{z}	_	1.0 *1	_	mV/°C	$*^{2} I_{z} = 5 \text{ mA}$ Ta = -20 to 25 to 75°C

Notes: 1. Type Value of γ_z : 1.0 mV/°C

2. Definition of γ_z γ_z based on Ta = + 25°C and the temperature coefficient with each temperature. (Range of operation temperature)

Main Characteristic

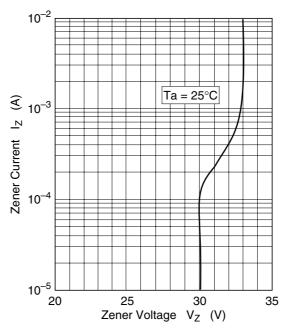


Fig.1 Zener current vs. Zener voltage

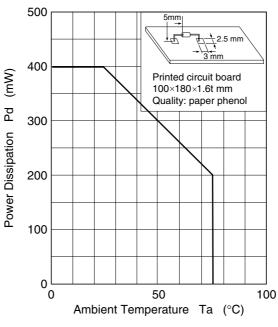
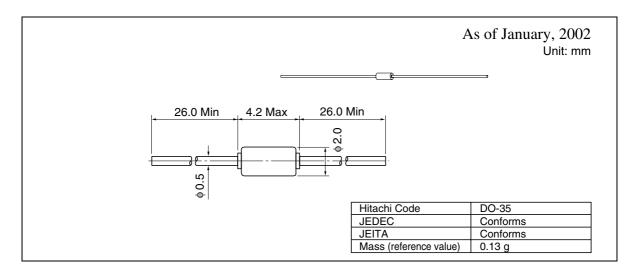


Fig.2 Power Dissipation vs. Ambient Temperature

HZT33

Package Dimensions



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